

500mW AXIAL LEAD ZENER DIODES

FEATURES

- Planar Die construction
- 500mW Power Dissipation
- Ideally Suited for Automated Assembly Processes
- Lead free in compliance with EU RoHS 2011/65/EU directive

MECHANICAL DATA

- Case: Molded glass DO-35
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 0.13 grams
- Ordering information: Suffix :"-35" to order DO-35 Package
- Packing information

B - 2K per Bulk box

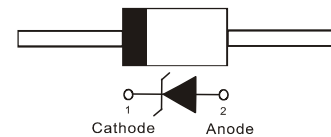
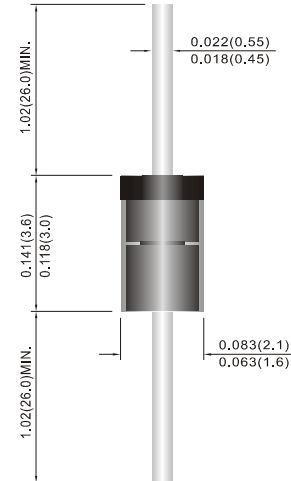
T/R - 10K per 15" plastic Reel

T/B - 5K per horiz. tape &

Ammo box

DO-35

Unit : inch(mm)



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Parameter	Symbol	Value	Units
Power Dissipation at Tamb = 25 °C	P _{TOT}	500	mW
Junction Temperature	T _J	175	°C
Storage Temperature Range	T _{STG}	-65 to +175	°C
Valid provided that leads at a distance of 8mm from case are kept at ambient temperature.			

Parameter	Symbol	Min.	Typ.	Max.	Units
Thermal Resistance Junction to Ambient Air	R _{θJA}	--	--	0.3	°C/mW
Forward Voltage at I _F = 100mA	V _F	--	--	1	V
Valid provided that leads at a distance of 10 mm from case are kept at ambient temperature.					

Part Number	Nominal Zener Voltage			Max. Zener Impedance				Max Reverse Leakage Current		marking code
	Vz @ IzT			ZzT @ IzT		Zzk @ Izk		IR @ VR		
	Nom. V	Min. V	Max. V	Ω	mA	Ω	mA	uA	V	
BZX55C2V4	2.4	2.28	2.56	85	5	600	1	50	1	BZX55C2V4
BZX55C2V7	2.7	2.5	2.9	85	5	600	1	10	1	BZX55C2V7
BZX55C3V0	3	2.8	3.2	85	5	600	1	4	1	BZX55C3V0
BZX55C3V3	3.3	3.1	3.5	85	5	600	1	2	1	BZX55C3V3
BZX55C3V6	3.6	3.4	3.8	85	5	600	1	2	1	BZX55C3V6
BZX55C3V9	3.9	3.7	4.1	85	5	600	1	2	1	BZX55C3V9
BZX55C4V3	4.3	4	4.6	75	5	600	1	1	1	BZX55C4V3
BZX55C4V7	4.7	4.4	5	60	5	600	1	0.5	1	BZX55C4V7
BZX55C5V1	5.1	4.8	5.4	35	5	550	1	0.1	1	BZX55C5V1
BZX55C5V6	5.6	5.2	6	25	5	450	1	0.1	1	BZX55C5V6
BZX55C6V2	6.2	5.8	6.6	10	5	200	1	0.1	2	BZX55C6V2
BZX55C6V8	6.8	6.4	7.2	8	5	150	1	0.1	3	BZX55C6V8
BZX55C7V5	7.5	7	7.9	7	5	50	1	0.1	5	BZX55C7V5
BZX55C8V2	8.2	7.7	8.7	7	5	50	1	0.1	6	BZX55C8V2
BZX55C9V1	9.1	8.5	9.6	10	5	50	1	0.1	7	BZX55C9V1
BZX55C10	10	9.4	10.6	15	5	70	1	0.1	7.5	BZX55C10
BZX55C11	11	10.4	11.6	20	5	70	1	0.1	8.5	BZX55C11
BZX55C12	12	11.4	12.7	20	5	90	1	0.1	9	BZX55C12
BZX55C13	13	12.4	14.1	26	5	110	1	0.1	10	BZX55C13
BZX55C15	15	13.8	15.6	30	5	110	1	0.1	11	BZX55C15
BZX55C16	16	15.3	17.1	40	5	170	1	0.1	12	BZX55C16
BZX55C18	18	16.8	19.1	50	5	170	1	0.1	14	BZX55C18
BZX55C20	20	18.8	21.2	55	5	220	1	0.1	15	BZX55C20
BZX55C22	22	20.8	23.3	55	5	220	1	0.1	17	BZX55C22
BZX55C24	24	22.8	25.6	80	5	220	1	0.1	18	BZX55C24
BZX55C27	27	25.1	28.9	80	5	220	1	0.1	20	BZX55C27
BZX55C30	30	28	32	80	5	220	1	0.1	22	BZX55C30
BZX55C33	33	31	35	80	5	220	1	0.1	24	BZX55C33
BZX55C36	36	34	38	80	5	220	1	0.1	27	BZX55C36
BZX55C39	39	37	41	90	2.5	500	1	0.1	30	BZX55C39
BZX55C43	43	40	46	90	2.5	600	1	0.1	33	BZX55C43
BZX55C47	47	44	50	110	2.5	700	1	0.1	36	BZX55C47
BZX55C51	51	48	54	125	2.5	700	0.5	0.1	39	BZX55C51
BZX55C56	56	52	60	135	2.5	1000	0.5	0.1	43	BZX55C56
BZX55C62	62	58	66	150	2.5	1000	0.5	0.1	47	BZX55C62
BZX55C68	68	64	72	200	2.5	1000	0.5	0.1	51	BZX55C68
BZX55C75	75	70	79	250	2.5	1500	0.5	0.1	56	BZX55C75

STANDARD VOLTAGE TOLERANCE IS + 5% AND :

SUFFIX "A" FOR + 1%

SUFFIX "B" FOR + 2%

SUFFIX "C" FOR + 5%

SUFFIX "D" FOR + 20%

* MEASURED WITH PULSES Tp=40 mSec.

ZENER DIODE NUMBERING SYSTEM:

BZX55 C3V6

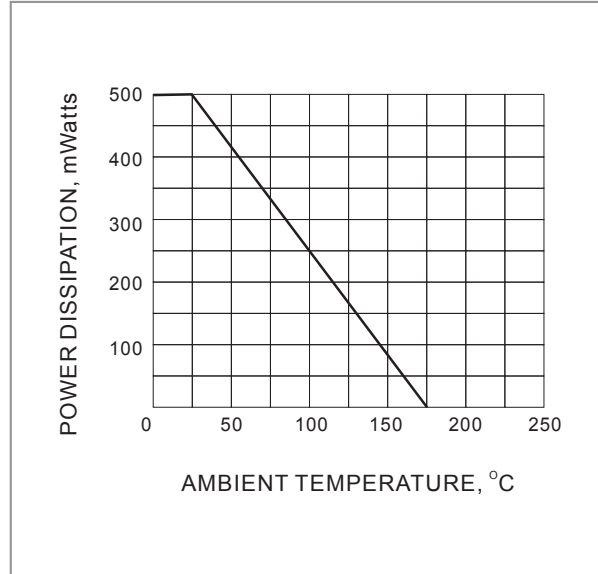
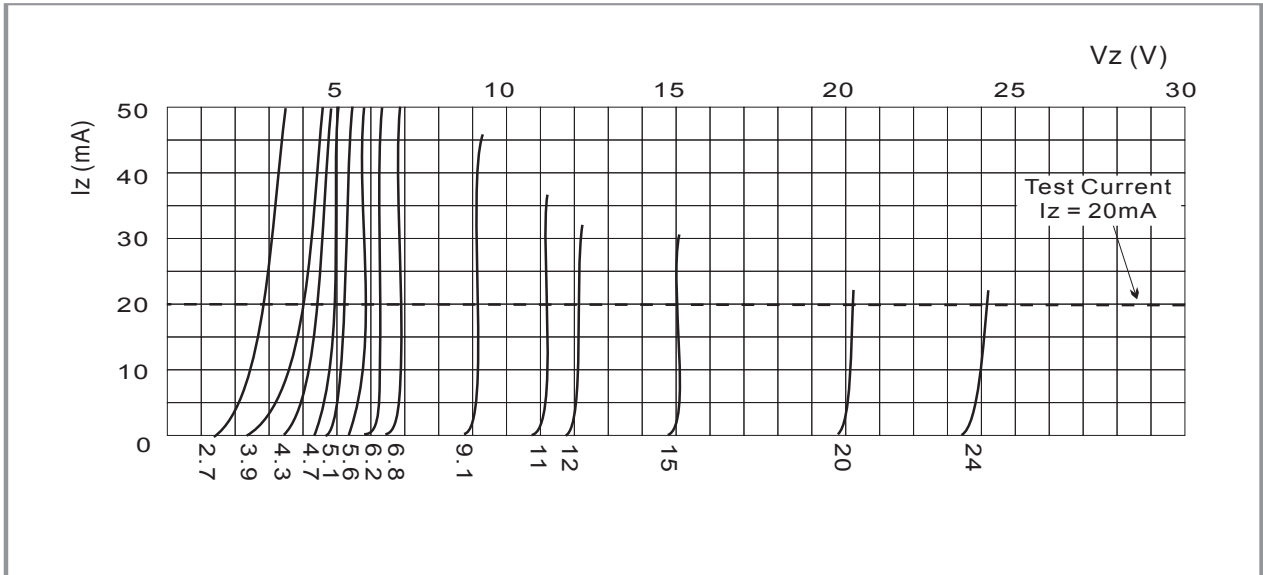
1* 2*

1* TYPENO.

2* VZ OF ZENERDIODE, V CODE IS INSTEADOF DECIMAL POINT.

3* e.g., 3V6=3.6V

* MEASURED WITH PULSES Tp=40 mSec.

RATING AND CHARACTERISTIC CURVES
FIG. 1 POWER DERATING CURVE

Fig.2 BREAKDOWN CHARACTERISTICS


Part No_packing code_Version

BZX55C2V4_AX_10001
 BZX55C2V4_AY_10001
 BZX55C2V4_R2_10001
 BZX55C2V4_B0_10001

For example :
RB500V-40_R2_00001


Packing Code XX				Version Code XXXXX		
Packing type	1 st Code	Packing size code	2 nd Code	HF or RoHS	1 st Code	2 nd ~5 th Code
Tape and Ammunition Box (T/B)	A	N/A	0	HF	0	serial number
Tape and Reel (T/R)	R	7"	1	RoHS	1	serial number
Bulk Packing (B/P)	B	13"	2			
Tube Packing (T/P)	T	26mm	X			
Tape and Reel (Right Oriented) (TRR)	S	52mm	Y			
Tape and Reel (Left Oriented) (TRL)	L	PANASERT T/B CATHODE UP (PBCU)	U			
FORMING	F	PANASERT T/B CATHODE DOWN (PBCD)	D			

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